

Title (en)

METHOD AND DEVICE FOR SEPARATING PRODUCTS WITH A CONTROLLED CUT EDGE, AND SEPARATED PRODUCT

Title (de)

VERFAHREN UND EINRICHTUNG ZUM TRENNEN VON PRODUKTEN MIT EINER GESTEUERTEN SCHNEIDKANTE UND GETRENNTES PRODUKT

Title (fr)

PROCEDE ET DISPOSITIF DE SEPARATION DE PRODUITS A L'AIDE D'UN BORD TRANCHE COMMANDE ET PRODUIT SEPRE

Publication

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Application

EP 06716694 A 20060321

Priority

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Abstract (en)

[origin: WO2006118454A1] The invention relates to a method for separating products, in particular semiconductor circuits, from a shared carrier by means of laser cutting. The invention also relates to a device for applying this method. The invention further also relates to a product, in particular a semiconductor mounted on a carrier, separated by means of a laser beam using such a method.

IPC 8 full level

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CPC (source: EP KR)

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Citation (search report)

See references of WO 2006118454A1

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